## **Technical Data Sheet**

# TAIYO PSR-4000BN Series

## LIQUID PHOTOIMAGEABLE SOLDER MASK

- Screen or Spray Application
- Available in Green or Dark GreenSemi-Gloss Finish
- **RoHS Compliant**
- We want to the second second
- **Solution** Compatible with Lead-Free Processing
- Best In Class for Small Hole Clearing
- **Wide Processing Window**
- **Solution** Fine Dam Resolution
- Withstands ENIG & Immersion Tin

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 TAIYO AMERICA, INC.

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# **Technical Data Sheet**

## **PROCESSING PARAMETERS FOR PSR-4000BN SERIES**

**PSR-4000BN** Series includes **PSR-4000BN**, **PSR-4000BN** (HV), and **PSR-4000BN** (DG). They are two-component, alkaline developable LPI solder mask products for flood screen and spray application methods. The products are designed to be user friendly with wide processing latitudes, low odor, fast developing and good resistance to alternate metal finishes such as ENIG and immersion Tin while maintaining dams of 3 mils or less. The **PSR-4000 BN** (HV) provides improved edge coverage over high circuits while the **PSR-4000BN** (DG) provides the same benefit in a Dark Green color. **PSR-4000BN Series** meets or exceeds the requirements of IPC SM-840C Class H and Class T, Bellcore GR-78-CORE Issue 1, and has a UL flammability rating of 94V-0. All Taiyo America products comply with the Directive 2002/95/EC of the European Parliament and of the Council of 27 January 2003 on the Restriction of the use of certain Hazardous Substances (RoHS) in electrical and electronic equipment.

PSR-4000BN SERIES COMPONENTS	PSR-4000BN Series/ CA-40BN			
	Mixing Ratio	100 parts		43 parts
	Color	Green		White
	Mixed Properties	s BN	HV	DG
	Solids	77%	77%	77%
	Viscosity	135-165ps	175-225ps	175-225ps
	Specific Gravity	1.39	1.39	1.39

MIXING
 PSR-4000BN Series is supplied in pre-measured containers with a mix ratio by weight of 100 parts PSR-4000BN and 43 parts CA-40BN. PSR-4000BN can be mixed by hand with a mixing spatula for 10 – 15 minutes. Mixing can be done with a mechanical mixer at low speeds to minimize shear thinning for 10 – 15 minutes. Also, mixing can be done with a paint shaker for 10 – 15 minutes.

**PRE-CLEANING** Prior to solder mask application, the printed circuit board surface needs to be cleaned. Various cleaning methods include Pumice, Aluminum Oxide, Mechanical Brush, and Chemical Clean. All of these methods will provide a clean surface for the application of **PSR-4000BN Series**. Hold time after cleaning the printed circuit board should be held to a minimum to reduce the oxidation of the copper surfaces.



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SCREEN PRINTING	<ul> <li>Method: Single Sided and Double Sided Screening</li> <li>Screen Mesh: 74 – 110</li> <li>Screen Mesh Angle: 22.5° Bias</li> <li>Screen Tension: 20 - 28 Newtons</li> <li>Squeegee: 60 – 80 durometer</li> <li>Squeegee Angle: 27 – 35°</li> <li>Printing Mode: Flood / Print / Print</li> <li>Flood Pressure: 20 – 30 psi</li> <li>Printing Speed: 2.0 – 9.9 inches/sec</li> <li>Printing Pressure: 60 – 100 psi</li> </ul>		
TACK DRY CYCLE	<ul> <li>The Tack Dry step is required to remove solvent from the solder mask film and produce a firm dry surface. The optimum dwell time and oven temperature will depend on oven type, oven loading, air circulation, exhaust rate, and ramp times. Excessive tack dry times and temperature will result in difficulty developing solder mask from through holes and a reduction in photo speed. Insufficient tack dry will result in artwork marking and/or sticking. Typical tack dry conditions for <b>PSR-4000BN Series</b> are as followed:</li> <li>Oven Temperature: 150 - 185°F (65 - 85°C)</li> <li>For Single-Sided (Batch Oven) <ul> <li>1<sup>st</sup> Side:</li> <li>Dwell Time: 10 - 20 minutes</li> <li>2<sup>nd</sup> Side:</li> <li>Dwell Time: 25 - 45 minutes</li> </ul> </li> <li>For Double-Sided (Conveyorized or Batch Oven)</li> <li>Dwell Time: 25 - 60 minutes</li> </ul>		

EXPOSURE PSR-4000BN Series requires UV exposure to define solder mask dams and features. The spectral sensitivity of PSR-4000BN Series is in the area of 365 nm. Exposure times will vary by bulb type and age of the bulb. Below are guidelines for exposing PSR-4000BN Series.

- Exposure Unit: 5 kW or higher
- Stouffer Step 21: Clear 8 minimum (on metal / under phototool)
- Energy: 250 mJ / cm<sup>2</sup> minimum (under phototool)

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Page 4 of 6

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**Technical Data Sheet** 

## **PROCESSING PARAMETERS FOR PSR-4000BN SERIES**

**DEVELOPMENT PSR-4000BN Series** is developed in an aqueous sodium or potassium carbonate solution. Developing can be done in either a horizontal or vertical machine.

- Solution: 1% by wt. Sodium Carbonate or 1.2% Potassium Carbonate
- pH: 10.6 or greater
- Temperature: 85 105°F (29 41°C)
- Spray Pressure: 25 45 psi
- Dwell Time in developing chamber: 45 90 seconds
- Water rinse is needed to remove developer solution followed by a drying step

**FINAL CURE PSR-4000BN** needs to be thermally cured to insure optimal final property performance. Thermal curing can be done in a batch oven or conveyorized oven.

- Temperature: 275 300°F (135 149°C)
- Time at Temperature: 45 60 minutes

For Process Optimization please contact your local Taiyo America Representative



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## FINAL PROPERTIES FOR PSR-4000BN

### IPC-SM-840C, Class H & T, Solder Mask Vendor Testing Requirements

TEST	SM-840 PARAGRAPH	REQUIREMENT	RESULT
Visual	3.4.8	Uniform in Appearance	Pass
Curing	3.4.5	Ref: 3.6.1.1, 3.7.1 and 3.7.2	Pass
Non-Nutrient	3.4.6	Does not contribute to biological growth	Pass
Dimensional	3.4.10	No Solder Pickup and Withstand 500 VDC	Pass
Pencil Hardness	3.5.1	Minimum "F"	Pass – 8H
Adhesion	3.5.2	Rigid – Cu, Ni, FR-4	Pass
Machinability	3.5.3	No Cracking or Tearing	Pass
Resistance to Solvents			
and Cleaning Agents	3.6.1.1	Table 3 Solvents	Pass
Hydrolytic Stability and	3.6.2	No Change after 28 days of 95-99°C	
Aging		and 90-98% RH	Pass
Solderability	3.7.1	No Adverse Effect J-STD-003	Pass
Resistance to Solder	3.7.2	No Solder Sticking	Pass
Dielectric Strength	3.8.1	500 VDC / mil Minimum	2800 VDC/mil
Thermal Shock	3.9.3	No Blistering, Crazing or De-lamination	Pass

#### **Specific Class "H" Requirements**

	SM-840		
TEST	PARAGRAPH	REQUIREMENT	RESULT
			Pass – File #E166421
			UL Name:
Flammability	3.6.3	UL 94V-0	PSR-4000BN / CA-40BN
			PSR-4000BN (HV) / CA-40BN
			PSR-4000BN (DG) / CA-40BN
Insulation Resistance	3.8.2		
Before Soldering		5 x 10 <sup>8</sup> ohms minimum	Pass (1.29 x 10 <sup>13</sup> ohms)
After Soldering		5 x 10 <sup>8</sup> ohms minimum	Pass (3.31 x 10 <sup>13</sup> ohms)
Moisture & Insulation Resistance	3.9.1		
Before Soldering–In Chamber		5 x 10 <sup>8</sup> ohms minimum	Pass (6.61 x 10 <sup>10</sup> ohms)
Before Soldering–Out of Chamber		5 x 10 <sup>8</sup> ohms minimum	Pass (2.50 x 10 <sup>12</sup> ohms)
After Soldering-In Chamber		5 x 10 <sup>8</sup> ohms minimum	Pass (1.89 x 10 <sup>10</sup> ohms)
After Soldering-Out of Chamber		5 x 10 <sup>8</sup> ohms minimum	Pass (1.07 x 10 <sup>13</sup> ohms)
Electrochemical Migration	3.9.2	>2.0 x 10 <sup>6</sup> ohms, no	Pass (1.35 x 10 <sup>12</sup> ohms)
		dendritic growth	

### **Specific Class "T" Requirements**

	SM-840		
TEST	PARAGRAPH	REQUIREMENT	RESULT
Flammability	3.6.3	Bellcore 0 <sub>2</sub> Index – 28 minimum	Pass – 74
Insulation Resistance	3.8.2		
Before Soldering		5 x 10 <sup>8</sup> ohms minimum	Pass (2.23 x 10 <sup>9</sup> ohms)
After Soldering		5 x 10 <sup>8</sup> ohms minimum	Pass (1.14 x 10 <sup>13</sup> ohms)



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## FINAL PROPERTIES FOR PSR-4000BN

Specific Class "T" Requirements				
	SM-840			
TEST	PARAGRAPH	REQUIREMENT	RESULT	
Moisture & Insulation Resistance	3.9.1			
Before Soldering–In Chamber		5 x 10 <sup>8</sup> ohms minimum	Pass (1.77 x 10 <sup>9</sup> ohms)	
Before Soldering–Out of Chamber		5 x 10 <sup>8</sup> ohms minimum	Pass (1.80 x	
			10 <sup>13</sup> ohms)	
After Soldering-In Chamber		5 x 10 <sup>8</sup> ohms minimum	Pass (2.78 x	
			10 <sup>10</sup> ohms)	
After Soldering-Out of Chamber		5 x 10 <sup>8</sup> ohms minimum	Pass (2.31 x 10 <sup>13</sup> ohms)	
			10 <sup>13</sup> ohms)	
Electrochemical Migration	3.9.2	< 1 decade drop, no dendritic growth	Pass	

#### Additional Tests / Results

TEST		REQUIREMENT	RESULT
Dielectric Constant		Internal Test at 1 MHz	4.5
Dissipation Factor		Internal Test at 1 MHz	0.0290
CTE		Internal Test ( $\alpha 1/\alpha 2$ )	70 / 140 ppm
Outgassing Test ASTM E-595-90		TML ≤ 1%	TML-0.51%
A 2 J/cm <sup>2</sup> UV Cure was done after thermal cure.		CVCM ≤ 0.10%	CVCM-0.02%
Electroless Nickel / Immersion Gold Resistance		Nickel(85C/30 min)Tape Test Adhesion	Pass
Solvent Resistance Acet	tone:	No attack – 24 hours	Pass
Ν	MEK:	No attack – 24 hours	Pass
	IPA:	No attack – 24 hours	Pass
	PMA:	No attack – 24 hours	Pass
Acid Resistance HCI – 7	10%:	No attack – 30 Minutes	Pass
$H_2SO_4 - 2$	10%:	No attack – 30 Minutes	Pass
Base Resistance NaOH – 7		No attack – 30 Minutes	Pass
Boiling Water Resista	ance:	No attack – 15 Minutes	Pass
Solder / Flux Resistance (Alphametals)			
Alpha 857 water sol		No attack – 1 x 10 sec float (260C)	Pass
NR060 no-c		No attack – 1 x 10 sec float (260C)	Pass
3355-NB rosin-ba		No attack – 1 x 10 sec float (260C)	Pass
NR-3000A4 no-clean:		No attack – 1 x 10 sec float (260C)	Pass
Solder/Flux Resistance(Multicore) X32-10M no-clean:		No attack – 1 x 10 sec float (260C)	Pass
X32-06l no-c		No attack – 1 x 10 sec float (260C)	Pass
Solder/Flux Resistance-(Sanwa) SR-270 roba	osin- ased:	No attack – 1 x 10 sec float (260C)	Pass
Conformal Coating Adhesion: Humiseal 1 B31 acrylic:		Crosscut (10/10) after tape	100/100
Humiseal 1A20 urethane:		Crosscut (10/10) after tape	100/100
Dow Corning 3-1753 silic	cone:	Crosscut (10/10) after tape	100/100
Glue Dot Adhesion – Loctite 3609		Adhesion of Glue Dot to PSR-4000BN	Excellent

Taiyo America, Inc. (TAIYO) warrants its products to be free from defects in materials and workmanship for the specified warranty period (PSR-4000BN / CA-40BN Warranty period is 12 Months) provided the customer has, at all times, stored the ink at a temperature of 68°F or less. TAIYO accepts no responsibility or liability for damages, whether direct, indirect, or consequential, resulting from failure in the performance of its products. If a TAIYO product is found to be defective in material or workmanship, its liability is limited to the purchase price of the product found to be defective. TAIYO MAKES NO OTHER WARRANTY, EXPRESS OR IMPLIED, AND MAKES NO WARRANTY OF MERCHANTABILITY OR OF FITNESS FOR ANY PARTICULAR PURPOSE. TAIYO'S obligation under this warranty shall not include any transportation charges or costs of installation or any liability for direct, indirect, or consequential damages or delay. If requested by TAIYO, products for which a warranty claim is made are to be returned transportation prepaid to TAIYO'S factory. Any improper use or any alteration of TAIYO'S product by the customer, as in TAIYO'S judgment affects the product materially and adversely, shall void this limited warranty.



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